



Molding Power Inductor

GMPC1265HP-Serise(G)-D

1. Features

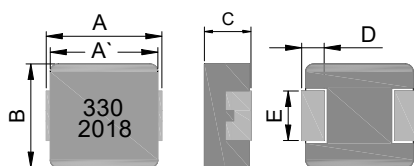
1. Carbonyl Powder.
2. Compact design.
3. High current , low DCR , high efficiency.
4. Very low acoustic noise and very low leakage flux noise.
5. High reliability.
6. 100% Lead(Pb)-Free and RoHS compliant.
7. Operating temperature -40~+125℃(Including self - temperature rise)



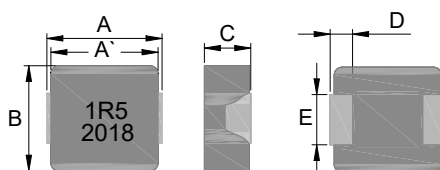
2. Applications

Note PC power system , incl. IMVP-6
DC/DC converter .

3. Dimensions



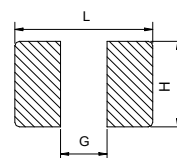
leadframe



non-leadframe



Recommend PC Board Pattern



Series	A(mm)	A'(mm)	B(mm)	C(mm)	D(mm)	E(mm)
GMPC1265HP	13.5±0.5	12.5±0.3	12.5±0.3	6.2±0.3	2.3±0.3	4.7±0.3

L(mm)	G(mm)	H(mm)
14.2	8.0	5.0

Note: 1. The above PCB layout reference only.
2. Recommend solder paste thickness at 0.15mm and above.

4. Part Numbering

GMPC	1265	HP	-	330	MG	-	D
A	B	C		D	E		F

A: Series

B: Dimension

C: Type

D: Inductance

E: Inductance Tolerance

F: Code

BxC

HP:H:Carbonyl Powder,P:PAD broaden.

330=33.0uH

M=±20%.

Marking: Black.330 and 2018(20 YY, 18 WW, follow production date).



5. Specification

Part Number	Inductance L0 (uH)±20%	I rms (A) Typ	I sat (A) Typ	DCR (mΩ) Typ. @25℃	DCR (mΩ) Max. @25℃	Type
GMPC1265HP-R22MG-D	0.22	53	112	0.47	0.60	non-leadframe
GMPC1265HP-R33MG-D	0.33	46	68	0.65	0.8	non-leadframe
GMPC1265HP-R36MG-D	0.36	45	66	0.7	0.9	non-leadframe
GMPC1265HP-R47MG-D	0.47	41	63	0.9	1.2	non-leadframe
GMPC1265HP-R56MG-D	0.56	37	58	1.05	1.2	non-leadframe
GMPC1265HP-R68MG-D	0.68	35	55	1.25	1.5	non-leadframe
GMPC1265HP-R82MG-D	0.82	33	50	1.5	1.9	non-leadframe
GMPC1265HP-1R0MG-D	1.00	30	48	1.7	2.3	non-leadframe
GMPC1265HP-1R5MG-D	1.50	27	45	2.5	3.0	non-leadframe
GMPC1265HP-2R2MG-D	2.20	22	37	3.8	4.2	leadframe
GMPC1265HP-3R3MG-D	3.30	18	30	5.7	6.8	leadframe
GMPC1265HP-4R7MG-D	4.70	13.5	28	7.0	8.4	leadframe
GMPC1265HP-5R6MG-D	5.60	12.5	23	8.5	10	leadframe
GMPC1265HP-6R8MG-D	6.80	11.5	18	9.5	11.5	leadframe
GMPC1265HP-8R2MG-D	8.20	10.5	16	12	15.5	leadframe
GMPC1265HP-100MG-D	10.0	10.0	15.5	13.2	16.5	leadframe
GMPC1265HP-150MG-D	15.0	9	13	23.2	28	leadframe
GMPC1265HP-220MG-D	22.0	9	12	32.5	37	leadframe
GMPC1265HP-330MG-D	33.0	8	11	48	58	leadframe
GMPC1265HP-470MG-D	47.0	6.5	9.5	76	90	leadframe
GMPC1265HP-680MG-D	68.0	4.8	7.8	110	130	leadframe
GMPC1265HP-101MG-D	100	4.2	5.5	145	165	leadframe

Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25℃ ambient.
3. Testing Instrument(or equ) : L: HP4284A,CH11025,CH3302,CH1320,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40℃
5. Saturation Current (Isat) will cause L0 to drop approximately30%.
6. The part temperature (ambient + temp rise) should not exceed 125℃under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.



6. Typical Performance Curves

